

ON Semiconductor®

FDN335N

N-Channel 2.5V Specified PowerTrench™ MOSFET

General Description

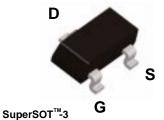
This N-Channel 2.5V specified MOSFET is produced using ON Semiconductor's advanced PowerTrench process that has been especially tailored to minimize the on-state resistance and yet maintain low gate charge for superior switching performance.

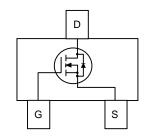
Applications

- DC/DC converter
- Load switch

Features

- 1.7 A, 20 V. $R_{DS(ON)}=0.07~\Omega~@V_{GS}=4.5~V$ $R_{DS(ON)}=0.100~\Omega~@V_{GS}=2.5~V.$
- Low gate charge (3.5nC typical).
- High performance trench technology for extremely low $R_{\scriptscriptstyle DS(ON)}$.
- High power and current handling capability.





Absolute Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V_{DSS}	Drain-Source Voltage		20	V
V_{GSS}	Gate-Source Voltage		<u>±</u> 8	V
I _D	Drain Current - Continuous	(Note 1a)	1.7	Α
	- Pulsed		8	
P_D	Power Dissipation for Single Operation	(Note 1a)	0.5	W
		(Note 1b)	0.46	
T_J,T_stg	Operating and Storage Junction Temperature Range		-55 to +150	∘C

Thermal Characteristics

$R_{\theta^{\mathrm{JA}}}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	250	°C/W
R _{OJC}	Thermal Resistance, Junction-to-Case	(Note 1)	75	°C/W

Package Outlines and Ordering Information

T donago o dimino di a ordorni g imormation				
Device Marking	Device	Reel Size	Tape Width	Quantity
335	FDN335N	7"	8mm	3000 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Char	acteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	20			V
ΔBV DSS ΔT_J	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$, Referenced to 25°C		14		mV/∘C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 16 V, V _{GS} = 0 V			1	μА
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 8 V, V _{DS} = 0 V			100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -8 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Char	acteristics (Note 2)					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.4	0.9	1.5	V
$\Delta VGS(th) \over \Delta T_J$	Gate Threshold Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}, \text{Referenced to } 25^{\circ}\text{C}$		-3		mV/∘C
R _{DS(ON)}	Static Drain-Source On-Resistance	$V_{GS} = 4.5 \text{ V}, I_D = 1.7 \text{ A}$ $V_{GS} = 4.5 \text{ V}, I_D = 1.7 \text{ A}, T_J = 125 ^{\circ}\text{C}$ $V_{GS} = 2.5 \text{ V}, I_D = 1.5 \text{ A}$		0.055 0.079 0.078	0.070 0.120 0.100	Ω
I _{D(on)}	On-State Drain Current	V _{GS} = 4.5 V, V _{DS} = 5 V	8			Α
g FS	Forward Transconductance	$V_{DS} = 5 \text{ V}, I_{D} = 1.5 \text{ A}$		7		S
Dynamic	Characteristics					
C _{iss}	Input Capacitance	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V},$		310		pF
C _{oss}	Output Capacitance	f = 1.0 MHz		80		pF
C _{rss}	Reverse Transfer Capacitance	7		40		pF
Switchin	g Characteristics (Note 2)			•	•	
t _{d(on)}	Turn-On Delay Time	V _{DD} = 10 V, I _D = 1 A,		5	15	ns
t _r	Turn-On Rise Time	$V_{GS} = 4.5 \text{ V}, R_{GEN} = 6 \Omega$		8.5	17	ns
t _{d(off)}	Turn-Off Delay Time			11	20	ns
t _f	Turn-Off Fall Time			3	10	ns
Q _g	Total Gate Charge	$V_{DS} = 10 \text{ V}, I_D = 1.7 \text{ A},$		3.5	5	nC
Q _{gs}	Gate-Source Charge	$V_{GS} = 4.5 V,$		0.55		nC
Q _{gd}	Gate-Drain Charge			0.95		nC
Drain-So	urce Diode Characteristics	and Maximum Ratings	_			
ls	Maximum Continuous Drain-Source	_			0.42	А
V _{SD}	Drain-Source Diode Forward	$V_{GS} = 0 \text{ V}, I_S = 0.42 \text{ A}$ (Note 2)		0.7	1.2	V

Notes:

1: R_{eJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{eJC} is guaranteed by design while R_{eCA} is determined by the user's board design.



a) 250°C/W when mounted on a 0.02 in² Pad of 2 oz. Cu.



b) 270°C/W when mounted on a minimum pad.

Scale 1 : 1 on letter size paper

2: Pulse Test: Pulse Width $\leq 300~\mu\text{s},~\text{Duty Cycle} \leq 2.0\%$

Typical Characteristics

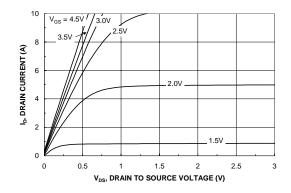


Figure 1. On-Region Characteristics.

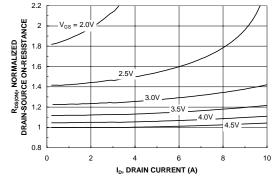


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

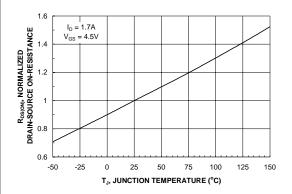


Figure 3. On-Resistance Variation with Temperature.

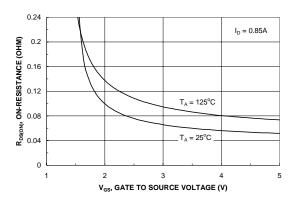


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

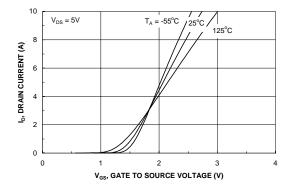


Figure 5. Transfer Characteristics.

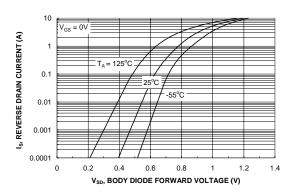
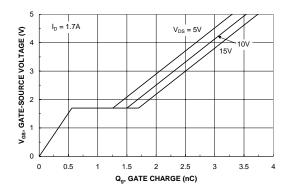


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics (continued)



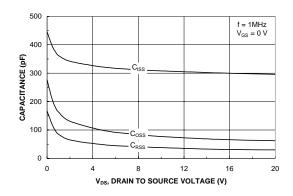
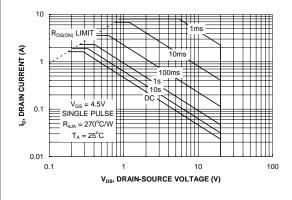


Figure 7. Gate Charge Characteristics.

Figure 8. Capacitance Characteristics.



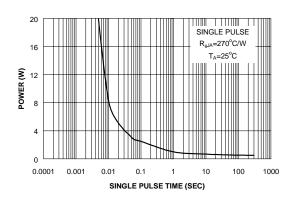


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

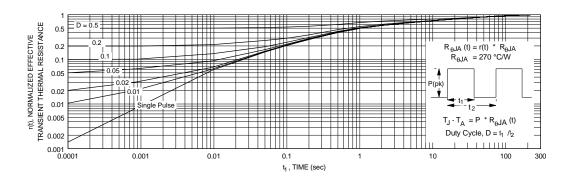


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1b. Transient themal response will change depending on the circuit board design.

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